(54) FLAME-RETARDANT ELECTRIC[illegible]MATERIAL COMPOSITION HAVING EXCELLENT HIGH-SPEED MOLDABILITY
(11) 62-11746 (A) (43) 20.1.1987 (19) JP
(21) Appl. No. 60-149948 (22) 10.7.1985
(71) NIPPON PETROCHEM CO LTD (72) MASAJI SUNADA(3)
(51) Int. Cl⁴. C08L23/08,C08K3/22//(C08L23/08,C08L23:16)

PURPOSE: To obtain the titled composition having excellent mechanical strength, electrical characteristics and abrasion resistance, by adding a specific amount of an inorganic flame-retardant to a resin component obtained by compounding a specific ethylene-ethyl acrylate copolymer with a specific ethylene-α-olefin copolymer at a specific ratio.

CONSTITUTION: The objective composition can be produced by compounding (A) 70~97 (wt)% ethylene-ethyl acrylate copolymer having a melt index (MI) of 0.2~5g/10 min, preferably 0.5~2g/10 min and an ethyl acrylate content of 5~20%, preferably 10~17% with (B) 3~30T ethylene-α-olefin copolymer (preferably propylene, etc.) having an MI of $\leqq$2g/10 min, preferably 0.01~1.8g/10 min, a density of 0.94~0.97g/cm^3 and a melt-tension (MT) at 190°C satisfying the formula $MT \geqq 6.0 \times MI^{-0.314}$, and mixing 100pts. (wt.) of the obtained resin composition with (C) 40~150pts., preferably 70~120pts. of an inorganic flame-retardant (preferably magnesium hydroxide, etc., having an average particle diameter of $\leqq 20\mu$m).

EFFECT: A non-polluting composition having low smoking tendency.

USE: Insulation material for communication cable.

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(54) FILM FOR HEAT-SEALING
(11) 62-11747 (A) (43) 20.1.1987 (19) JP
(21) Appl. No. 61-166670 (22) 17.7.1986
(71) DENKI KAGAKU KOGYO K.K. (72) TSUGUO HASEGAWA(2)
(51) Int. Cl⁴. C08L23/08,C08J5/18,C08L23/08,C08L25/06,C08L51/00,C08L53/02

PURPOSE: To provide a heat-sealing film having excellent heat-sealability, releasable easily in opening, and suitable especially for the heat-sealing of a vessel made of a styrene-based resin, by compounding specific components such as ethylene-acrylate copolymer, at specific ratios.

CONSTITUTION: The objective film for heat-sealing is produced from a resin composition composed of (A) 5~50 (wt)% ethylene-acrylate copolymer (preferably containiing 5~35% acrylate unit), (B) 5~50% styrene-butadiene block copolymer having styrene content of 10~50% and (C) 10~80% polystyrene and/or a high-impact styrene-butadiene graft copolymer (containing styrene as stem polymer).

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(54) RESIN COMPOSITION
(11) 62-11748 (A) (43) 20.1.1987 (19) JP
(21) Appl. No. 60-150089 (22) 10.7.1985
(71) TOYO SEIKAN KAISHA LTD (72) SHIGEZO NOHARA(2)
(51) Int. Cl⁴. C08L23/12,C08K3/22,C08L23/26,C08L29/04

PURPOSE: To provide a resin composition having suppressed thermal degradation of a constituent copolymer in molding and giving a reusable scrap composition such as regrind, by compounding a propylene-based resin, an ethylene-vinyl alcohol copolymer and a hydrotalcite-type compound metal hydroxide.

CONSTITUTION: The objective resin composition can be produced by compounding (A) a propylene-based resin (e.g. isotactic polypropyene) with (B) an ethylene-vinyl alcohol copolymer (preferably a saponified copolymer produced by saponifying an ethylene-vinyl acetate copolymer having an ethylene content of 25~50 mol% to a saponification degree of $\geqq$00 mol%) and (C) a hydrotalcite-type compound metal hydroxide (preferably the hydroxide of formula). The ratio of A:B is preferably 10^6:1~1:10^2, and the amount of the component C is 10^{-5}~1 wt% based on the sum of the components A and B.

$Mg_{4.5}Al_2(OH)_{13}CO_3 \cdot 3.5H_2O$

EFFECT: The scorch, deposition to die face, etc., can be suppressed to give a molded article having excellent appearance and mechanical characteristics.